CLAIMS

We claim:

1.

 A method of manufacturing a liquid crystal micro display (lcmd), said method comprising:

> creating a hole in a substrate; causing liquid crystal material to flow through said hole; and sealing said hole.

- 2. The method of claim 1, further comprising: testing said lcmd after sealing said hole.
- 3. The method of claim 2, further comprising:
 separating said lemd from other lemds after testing said lemd.
- 4. The method of claim 1, wherein said substrate is a semiconductor substrate.
- 5. The method of claim 4, wherein the semiconductor substrate comprises an integrated circuit.
- 6. The method of claim 4, wherein the semiconductor substrate is part of a silicon wafer.
- 7. The method of claim 1, wherein said substrate comprises glass.
- 8. The method of claim 1, wherein said hole is sealed using a sealant material selected from a group consisting of glue, epoxy, and solder.

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9.	A method of manufacturing a first liquid crystal micro display (lcmd) comprising
	testing said first lcmd while it is physically connected to a second lcmd;
	and
	separating said first lcmd from said second lcmd after said testing.

- The method of claim 9, wherein said first lcmd comprises a semiconductor 10. substrate having an integrated circuit and a glass substrate having a transparent electrode.
- The method of claim 10, wherein said integrated circuit comprises electrodes. 11.
- The method of claim 11, wherein said testing includes causing a voltage 12. difference between the integrated circuit electrodes and the transparent electrode.
- The method of claim 12, wherein said testing includes determining whether the 13. lcmd produces a uniform image.
- A liquid crystal micro display (lcmd) comprising: 14. a first substrate; and a second substrate having a hole extending through a thickness thereof.
- The lcmd of claim 14, wherein said hole can be used for filling the lcmd with 15. liquid crystal material.
- The lcmd of claim 14, wherein the second substrate is a semiconductor substrate 16. comprising an integrated circuit.
- The lcmd of claim 14, wherein the second substrate comprises glass. 17.

18. The lcmd of claim 14, wherein said lcmd is physically connected to other lcmds.